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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>[initials]</i>	5,072,075	12/1991	Lee et al.			
<i>[initials]</i>	5,121,190	6/1992	Hsiao et al.			
<i>[initials]</i>	5,483,421	1/1996	Gedney et al.			
<i>[initials]</i>	5,574,630	11/1996	Kresge et al.			
<i>[initials]</i>	5,615,087	3/1997	Wieloch			
<i>[initials]</i>	5,798,563	8/1998	Feilchenfeld et al.			
<i>[initials]</i>	5,894,173	4/1999	Jacobs et al.			
<i>[initials]</i>	5,900,675	5/1999	Appelt et al.			
<i>[initials]</i>	4,882,454	11/1989	Peterson et al.			
<i>[initials]</i>	5,982,630	11/1999	Bhatia			
<i>[initials]</i>	5,926,377	7/1999	Nakao et al.			

10/06/551
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02/05/02

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
<i>[initials]</i>	9-232376	9/1997	Japan				
<i>[initials]</i>	10-209347	8/1998	Japan				
<i>[initials]</i>	11-87560	3/1999	Japan				
<i>[initials]</i>	2000-22071	1/2000	Japan				
<i>[initials]</i>	6-112271	4/1994	Japan				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>[initials]</i>	IBM Technical Disclosure Bulletin, Vol. 32, No. 3B, August 1989, "MULTILAYER POLYMER SUBSTRATE FOR DIRECT CHIP ATTACHMENT."
<i>[initials]</i>	PROCESS CONSIDERATIONS IN THE FABRICATION OF TEFLON PRINTED CIRCUIT BOARDS, Light et al., 1994 Proceedings, 44 Electronic Components & Technology Conference, 5/94.

EXAMINER

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